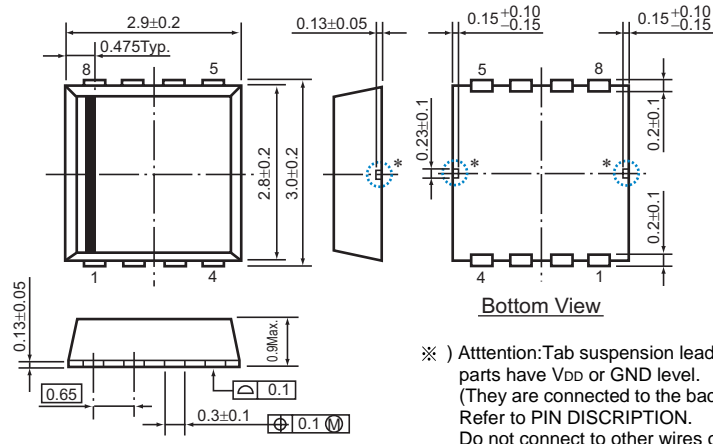


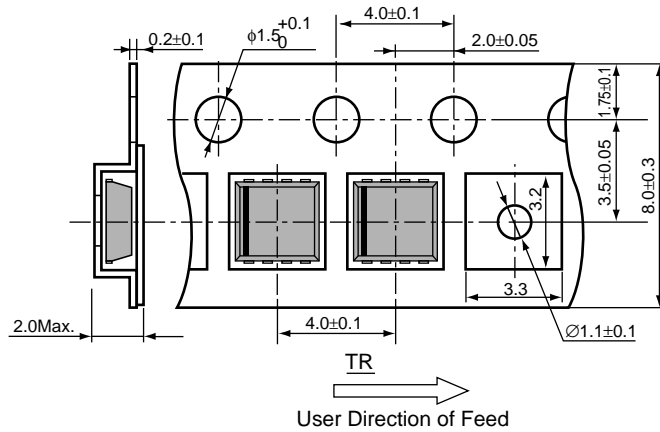
• SON-8

Unit: mm

PACKAGE DIMENSIONS

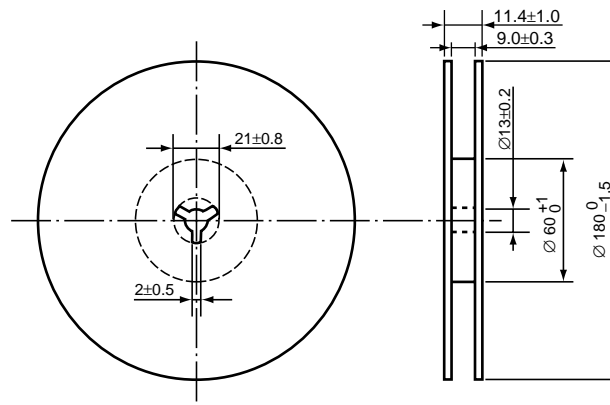


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-08Bc)

(1reel=3000pcs)



POWER DISSIPATION (SON-8)

This specification is at mounted on board. Power Dissipation (Pd) depends on conditions of mounting on board.

This specification is based on the measurement at the condition below:

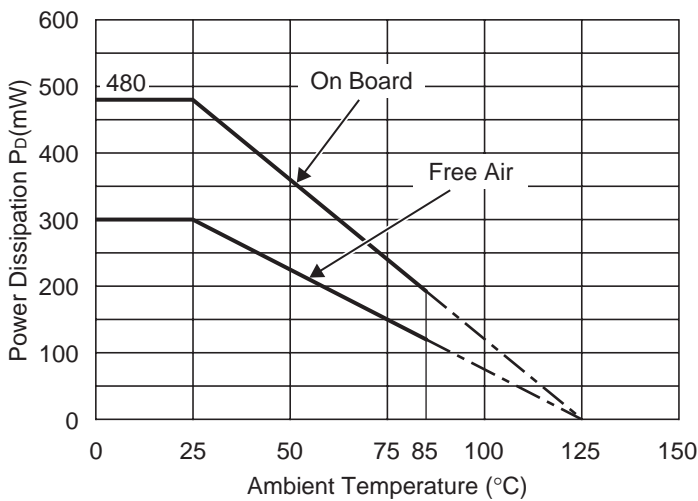
Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plactic (Double sided)
Board Dimensions	40mm × 40mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-hole	φ0.5mm × 44pcs

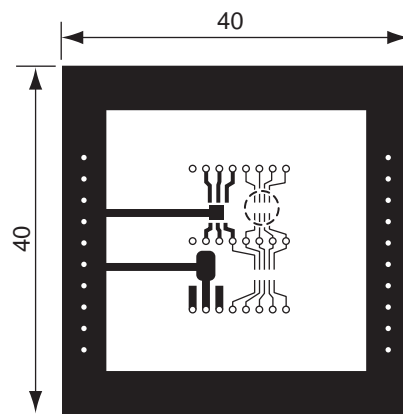
Measurement Result

(T_{opt}=25°C, T_{jmax}=125°C)

	Standard Land Pattern	Free Air
Power Dissipation	480mW	300mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}\text{C})/0.48\text{W}=208^{\circ}\text{C/W}$	333°C/W



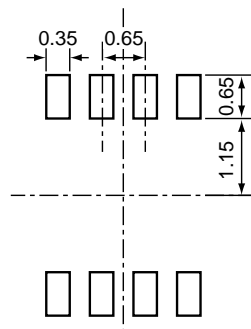
Power Dissipation



Measurement Board Pattern

○ IC Mount Area (Unit : mm)

RECOMMENDED LAND PATTERN



(Unit: mm)